

which is so related to each other that an undue burden would not be placed upon the Examiner by maintaining both groups of claims in a single application. See, e.g., MPEP § 803.

Next, please amend the application as follows and consider the remarks set forth below.

IN THE CLAIMS

Please amend claims 1-3, 5, 6, 9, 11, 13, 15, 16 and 17 in accordance with the following rewritten claims in clean form and add new claims 18-24. Applicant includes herewith an Attachment for Claim Amendments showing a marked up version of each amended claim.

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1. (Amended) A semiconductor device connecting structure for connecting a semiconductor device onto a substrate, characterized by comprising a bonding layer interposed between said semiconductor device and said substrate to accomplish adhesion therebetween, which includes a bonding material for adhering said semiconductor device onto said substrate and a plurality of spaces formed within said bonding material.

2. (Amended) A semiconductor device connecting structure as defined in claim 1, characterized in that said semiconductor device includes a plurality of bumps arranged in rows, and that said plurality of spaces are formed between said bump rows,

outside said bump rows and between said pumps, or at least within at least one of the areas therein.

C1 3. (Twice Amended) A semiconductor device connecting structure as defined in claim 1, characterized in that said plurality of spaces are placed closely to each other.

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C2 5. (Twice Amended) A semiconductor device connecting structure as defined in claim 1, characterized in that the percentage of said plurality of spaces within said bonding material is 5% to 70%.

6. (Twice Amended) A semiconductor device connecting structure as defined in claim 5, characterized in that the percentage of said plurality of spaces within said bonding material is 10% to 30%.

9. (Amended) A semiconductor device connecting method for connecting a semiconductor device onto a substrate, characterized by comprising the steps of:

C3 interposing a bonding layer between said semiconductor device and said substrate to accomplish adhesion therebetween;

Sub D33 joining said substrate and said semiconductor device to each other by pressing a pressurizing head, heated up to a high temperature, against said semiconductor device to pressurize and heat said bonding layer; and

forming a plurality of spaces within said bonding layer.

11. (Amended) A liquid crystal display unit comprising:

a pair of liquid crystal holding substrates disposed in an opposed relation to each other with liquid crystal therebetween;

a semiconductor device connected onto at least one of said liquid crystal holding substrate; and

a bonding layer interposed between said liquid crystal holding substrate and said semiconductor device to accomplish adhesion therebetween, characterized in that

said bonding layer includes a bonding material for adhering said semiconductor device onto said liquid crystal holding substrate and a plurality of spacers formed within said bonding material.

13. (Twice Amended) A liquid crystal display unit as defined in claim 11, characterized in that said plurality of spaces are placed closely to each other.

15. (Twice Amended) A liquid crystal display unit as defined in claim 11, characterized in that the percentage of said plurality of spaces within said bonding material is 5% to 70%.

16. (Twice Amended) A liquid crystal display unit as defined in claim 15, characterized in that the percentage of said plurality of spaces within said bonding material is 10% to 30%.

17. (Amended) An electronic apparatus having a plurality of semiconductor driving output terminals and a liquid crystal display unit connected to said semiconductor driving output terminals, characterized in that said liquid crystal display unit includes:

a pair of liquid crystal holding substrates disposed in an opposed relation to each other with liquid crystal therebetween;

C6 a semiconductor device connected onto at least one of said liquid crystal holding substrates; and

a bonding layer interposed between said liquid crystal holding substrate and said semiconductor device to accomplish adhesion therebetween,

wherein said bonding layer includes a bonding material for adhering said semiconductor device onto said liquid crystal holding substrate and a plurality of spaces formed within said bonding material.

Please add the following new claims:

18. (New) A semiconductor device connecting structure comprising:

C7 a substrate;

a semiconductor device connected to the substrate; and

a bonding layer interposed between the substrate and the semiconductor device, the bonding layer including a bonding material adhering the semiconductor

device to the substrate, a plurality of conductive particles dispersed in the bonding material, and a plurality of spaces formed within said bonding material,

wherein the semiconductor device is adhered to the substrate by the bonding material at a substantially plane center portion of the semiconductor device.

19. (New) A liquid crystal display comprising:

a substrate;

a liquid crystal on the substrate;

a plurality of electrodes on the substrate;

C7 a semiconductor device having a plurality of bumps, the semiconductor device being mounted on the substrate, each bump being connected to one of said plurality of electrodes;

a bonding layer interposed between the substrate and the semiconductor device, the bonding layer including a bonding material adhering the semiconductor device to the substrate, and a plurality of spaces formed within said bonding material,

wherein the plurality of spaces are at least formed in an area encompassed by the plurality of electrodes.

20. (New) A liquid crystal display comprising:

a substrate;

a liquid crystal on the substrate;

a semiconductor device mounted on the substrate, the semiconductor device including a periphery defining a mounting area;

a bonding layer interposed between the substrate and the semiconductor device, the bonding layer including a bonding material adhering the semiconductor device to the substrate, and a plurality of spaces formed within said bonding material, wherein the plurality of spaces are at least formed in the mounting area.

21. (New) A liquid crystal display according to claim 3, wherein a region occupied by the bonding layer is larger than the mounting area.

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22. (New) A liquid crystal display comprising:

- a substrate;
- a liquid crystal on the substrate;
- a plurality of electrodes on the substrate;
- a semiconductor device having at least two edges opposing each other, and a plurality of bumps aligned along at least said two edges,
- the semiconductor device being mounted on the substrate, each bump being connected to an electrode;
- a bonding layer interposed between the substrate and the semiconductor device, the bonding layer including a bonding material adhering the semiconductor device to the substrate, and a plurality of spaces formed within said bonding material, wherein the spaces are at least formed in an area bordered by the electrodes.

23. (New) A liquid crystal display comprising:

- a first substrate;
- a second substrate including an overlapping area overlapping the first substrate;
- a plurality of electrodes formed on the first substrate, each of the plurality of electrodes at least extending toward the overlapping area;
- a semiconductor device having a plurality of bumps, the semiconductor device being mounted on the substrate, each bump being connected to one of the plurality of electrodes;
- a bonding layer interposed between the substrate and the semiconductor device, the bonding layer including a bonding material adhering the semiconductor device to the substrate, and a plurality of spaces formed within said bonding material, wherein the plurality of spaces are at least formed in an area encompassed by the bumps.

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24. (New) A semiconductor device connecting structure comprising:

- a substrate;
- a semiconductor device connected to the substrate; and
- a bonding layer including a bonding material that joins the semiconductor to the substrate and a plurality of spaces disposed in the bonding material, the bonding layer being disposed between the substrate and the semiconductor device, wherein the semiconductor device is adhered to the substrate with the bonding material which is positioned between adjacent ones of the plurality of spaces.